

WHAT IS CLAIMED IS:

*Sub a*

1. A case for dissipating heat from an electronic device, comprising:  
an electronic circuit board;  
a heat generating electronic component disposed on said circuit board; and  
a housing positioned about said electronic circuit board and said heat generating electronic component; said housing being made of a thermally conductive material; said housing being in thermal communication with said electronic component with heat being dissipating from said heat generating electronic component and through said housing.
2. The case of Claim 1, wherein said thermally conductive material is a thermally conductive net-shape moldable polymer composition.
- 2 3.* The case of Claim 1, wherein said housing is injection molded.
- 3 4.* The case of Claim 1, wherein said heat generating electronic component is a semiconductor device.
- Sub b*  
5. A case for dissipating heat from an electronic device, comprising:  
an electronic circuit board;  
a heat generating electronic component disposed on said circuit board;  
a housing positioned about said electronic circuit board and said heat generating electronic component; said housing being of a thermally conductive material;  
a protrusion emanating from said housing corresponding and aligned with said heat generating electronic component; said protrusion emanating from said housing; and  
said protrusion being in thermal communication with said electronic component with heat being dissipating from said heat generating electronic component and through said housing via said protrusion.

6. The case of Claim 5, wherein said thermally conductive material is a thermally conductive net-shape moldable polymer composition.

7. The case of Claim 5, wherein said housing is injection molded.

8. The case of Claim 5, wherein said heat generating electronic component is a semiconductor device.

9. A case for dissipating heat from an electronic device, comprising:  
an electronic circuit board;  
a heat generating electronic component, having a top surface, disposed on said circuit board;  
an electromagnetic interference shield positioned on said electronic circuit board with said heat generating electronic component residing therebetween; said electromagnetic interference shield including a top surface with an aperture therethrough;  
a heat transfer conduit molded into and through said aperture; said heat transfer conduit being made of a thermally conductive material and having a top surface and a bottom surface;  
a housing, being made of a thermally conductive material, being in thermally communication with said top surface of said heat transfer conduit; said bottom surface of said heat transfer conduit being in thermal communication with said top surface of said heat generating electronic component;  
whereby heat is dissipated from said heat generating electronic component through said housing via said heat transfer conduit while said electromagnetic interference shield protects said heat generating electronic component from electromagnetic interference.

10. The case of Claim 1, wherein said thermally conductive material is a thermally conductive net-shape moldable polymer composition.

11. The case of Claim 1, wherein said housing and said heat transfer conduit are injection molded.

12. The case of Claim 1, wherein said heat generating electronic component is a semiconductor device.